
M24C08-F package mechanical data modifications

Silicon identification

This errata sheet applies to the M24C08-F, which is 8 Kbit serial I²C bus EEPROMs, and specifically to the devices delivered in 4-bump wafer-level chip-scale packages (WLCSP).

[Table 1](#) shows the list of part numbers.

Table 1. Device summary

Reference	Part Number
M24C08-F	M24C08-FCT6TP/T

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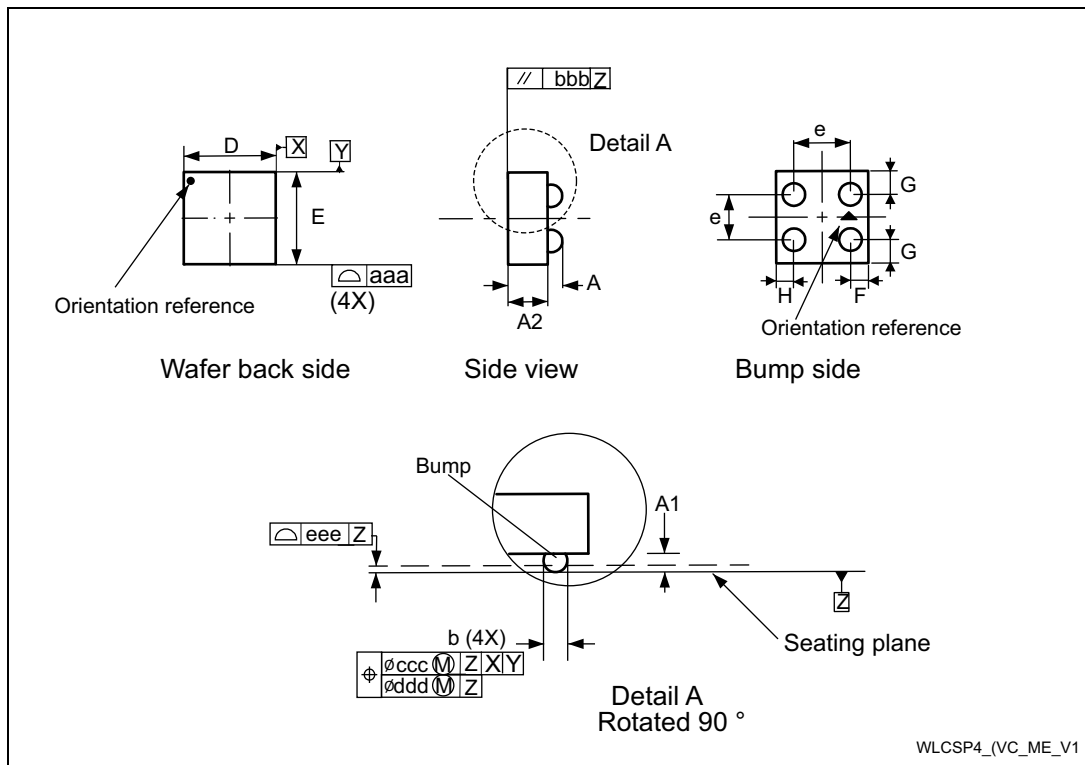
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1 M24C08-FCT physical product change

There isn't any physical product change.

Figure 1 shows the package outline.

Figure 1. WLCSP 4-bump, 0.703 x 0.713 mm, wafer level chip scale package outline



The figures below show the difference between D and E dimension in the front side view (see *Figure 2*), back side (see *Figure 3*) and side view (see *Figure 4*).

Figure 2. D and E front side view

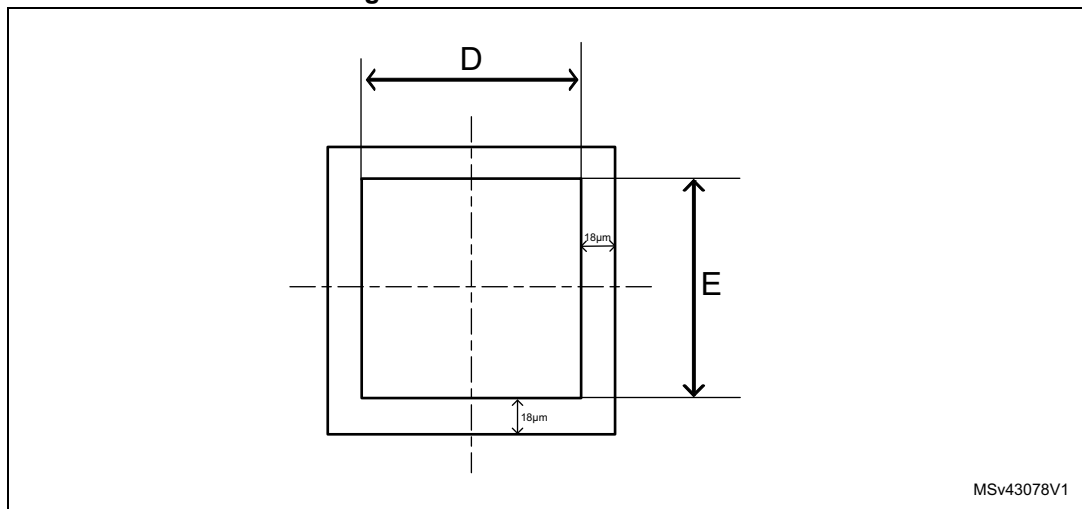


Figure 3. D and E back side view

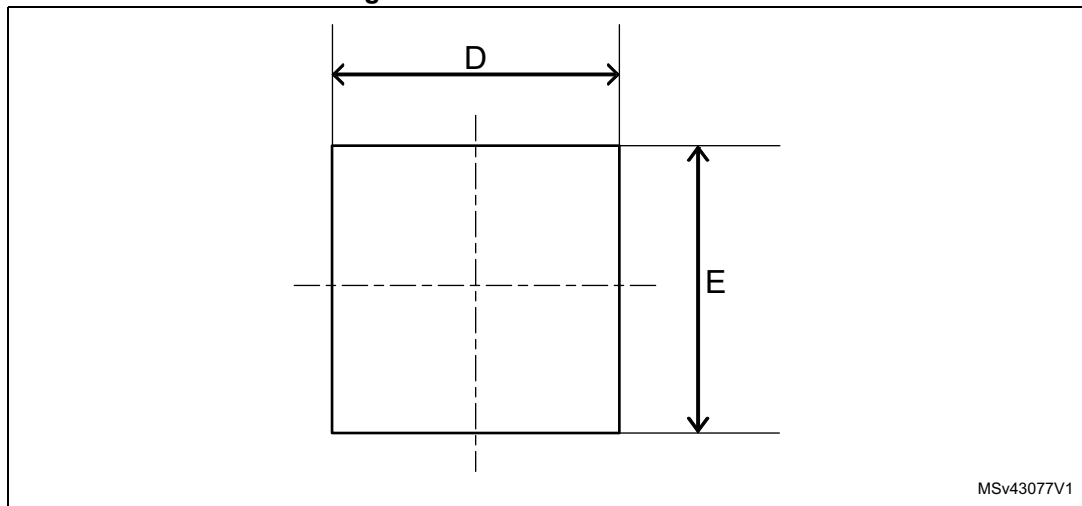
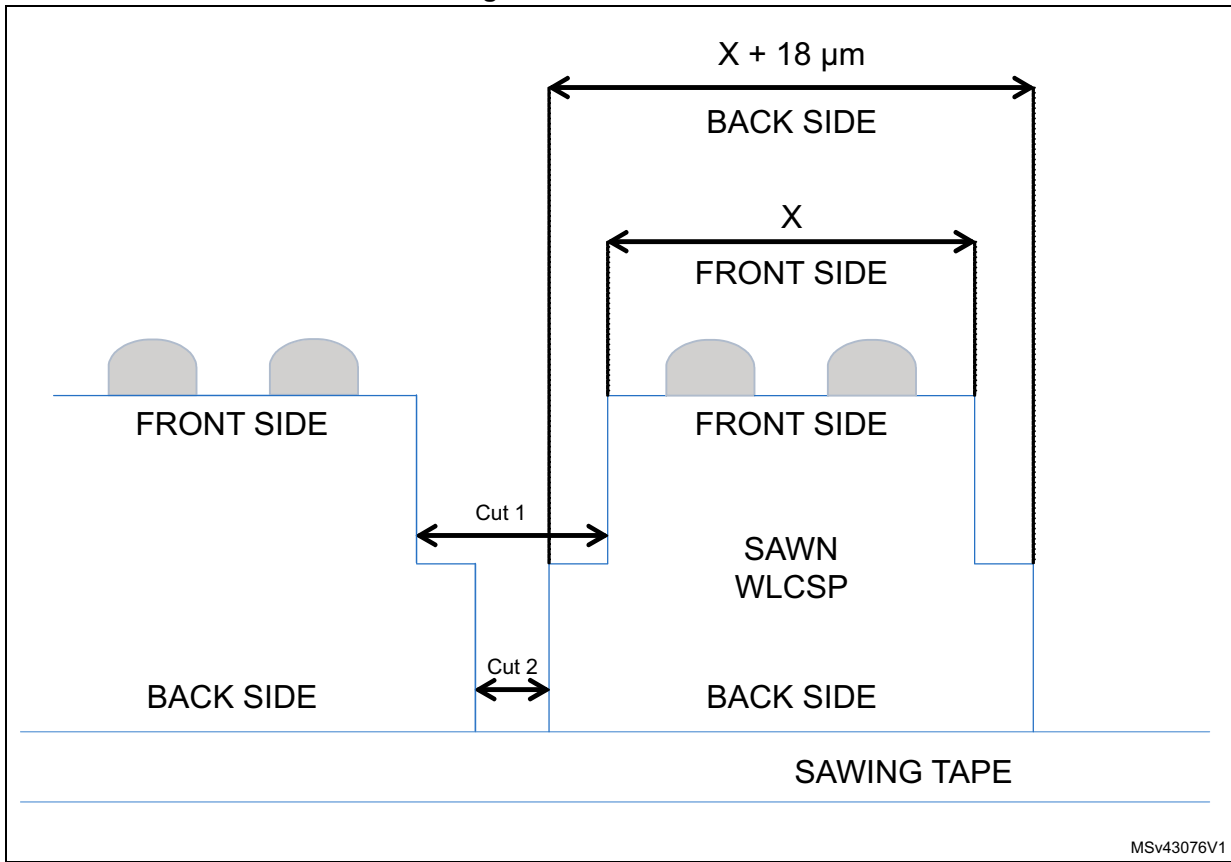


Figure 4. D or E side view



2 Package mechanical data modifications

This document refers to the changes of dimensions D and E (see [Figure 3](#)) described in the M24C08-F datasheet, in tables detailing the dimensions of the Thin WLCSP 4-bump package.

D and E values must be modified to correct the following mistake:

- The D and E values on M24C08-F datasheet corresponding to front side view (ball side) as shown in [Table 2](#), instead of back side view (marking side view) as shown in [Table 3](#).

Table 2. D and E values corresponding to front side view

Symbol	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
D	-	0.685	0.705	-	0.0270	0.0278
E	-	0.695	0.715	-	0.0274	0.0281

Table 3. D and E values corresponding to back side view

Symbol	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
D	-	0.703	0.723	-	0.0277	0.0285
E	-	0.713	0.733	-	0.0281	0.0289

The difference between back side and front side dimension is 18 μm (0.018 mm). This difference is due to two-step sawing process, where cut 1 and cut 2 are performed with blades having different thickness (see [Figure 4](#) in which X represents D or E and it has the same value and tolerance).

3 Revision history

Table 4. Document revision history

Date	Revision	Changes
13-Feb-2017	1	Initial release.

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